

**NON-PLANAR SURFACE FOR SEMICONDUCTOR CHIPS AND METHOD OF FORMING
THE NON-PLANAR SEMICONDUCTOR CHIP**

ABSTRACT OF THE DISCLOSURE

A semiconductor chip package having a non-planar chip
5 therein, to reduce the stress concentrations between the chip and
cover plate. In particular, a chip and method of forming a chip
having a non-planar or "domed" back surface, wherein the
thickness of the non-planar chip is greatest substantially near
the center of the chip. Further, a method of rounding the edges
10 or corners of the chip to reduce crack propagation originating at
the edges of the chip.